

TECHNICAL DATA SHEET

AF01-WNC Liquid flux



Version 1.1

Revision Date 10.08.2025

Description

AF01-WNC ARZIZ multicore liquid flux is considered to fulfill the strict requirements of the electronic industry for the purpose of soldering parts. This product removes oxides from the metal surfaces and enables them to be joined together by solder alloys. It is a water-based, rosin-free, halide-free and low-solid flux for surfaces with poor solderability from the pioneers of "no clean" technology.

Composition

Some data from chemical composition

Solids content	3.1 wt. %
Acid value (on liquid)	25 mg KOH/g
Halide content	None

Specification

Physical properties

Appearance	Colourless
Specific density at 25°C	1.007 g/cm ³
J-STD-004 Classification	ORL0
EN 29454 Classification	2.1.3
IPC-TM-650 Copper Mirror Test	pass

Application

The synthesized liquid flux is recommended for consumer electronics and general electrical soldering applications, particularly where high throughput is desirable. It may be used in foam, spray or wave application to remove oxide from the surface of base metal and prepare it for reliable soldering.

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RECOMMENDED OPERATING CONDITIONS

The Printed Circuit Board: AF01-WNC ARZIZ liquid flux is recommended for use on clean or oxidized copper. It will solder satisfactorily over most surface preservatives. It has been formulated to work over a wide range of solder resists. The solvent system in ARZIZ liquid flux has been designed for optimum wetting of surfaces. It is recommended that multicore ARZIZ Cleaner be used before applying the flux.

Fluxing: ARZIZ liquid flux has been formulated for use in spray fluxing only. The spray fluxing unit to 15-25 ml/min is recommended to prepare very clean surface ready for soldering.

Preheating: It is a water-based flux, so it is necessary to adjust preheat setting to ensure the water is sufficiently evaporated prior soldering. Excess moisture on the PCB during soldering may decrease the quality of the solder joints. ARZIZ recommendation is a speed of 1.2-1.5 m.min⁻¹ to reach the solder wave, a contact time of 1.5-3 seconds.

Health & safety

This Product has no serious harmful effect. For more information, please refer material safety data sheet.

Storage

Store the liquid flux in an originally sealed container in a cool and dry environment. The flux should not be stored below 10 °C. Lower temperature may cause the solids to crystallize and form a solid layer inside the container. If this happened, it can be tried to get solids back into solution by consistently stirring and heating it too room temperature. The product can be kept for 1 year after the date of delivery.

Packaging

The product is packaged in plastic bottles with different capacities of 1, 5 and 20 L.